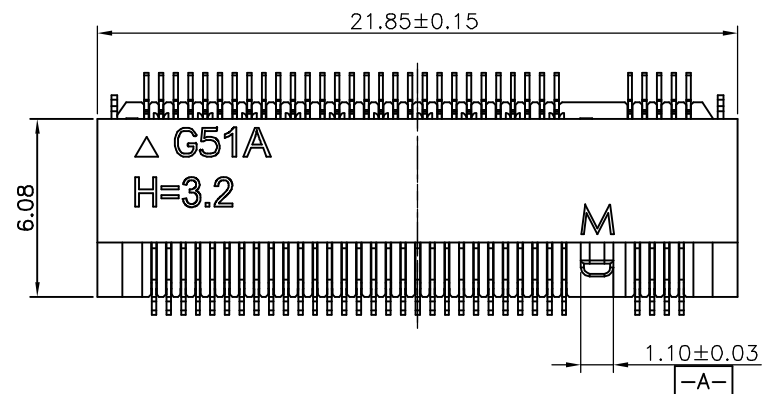
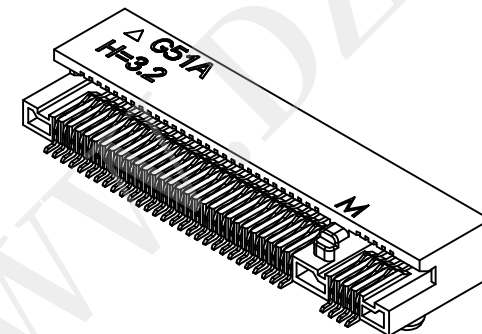


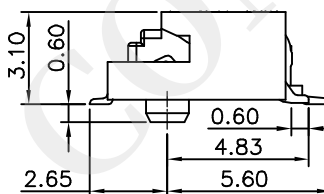
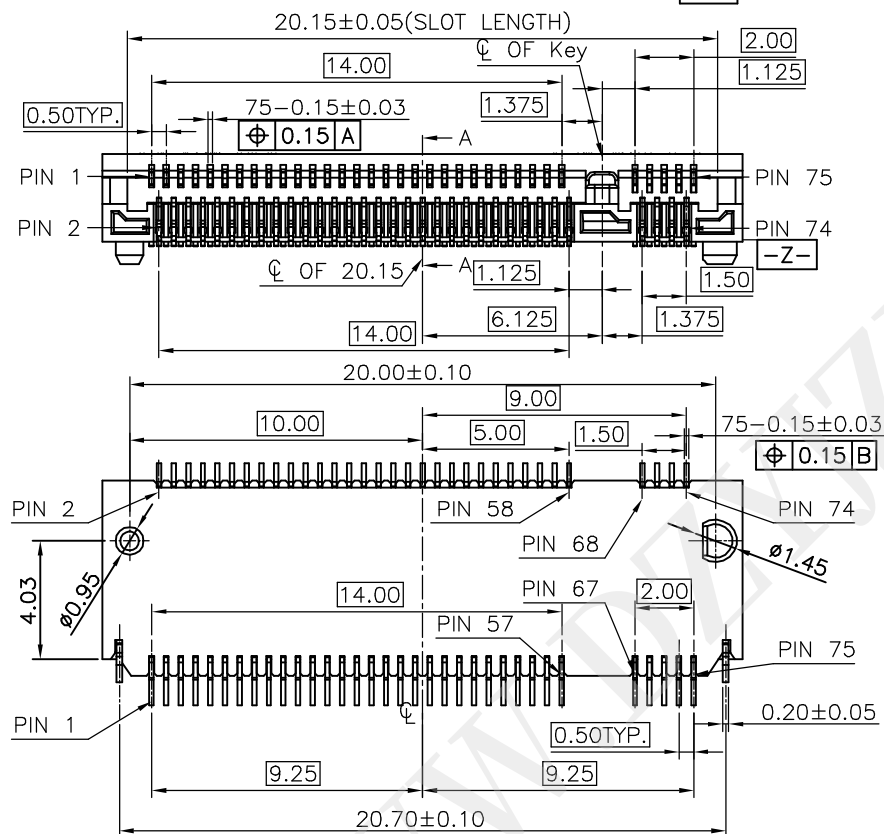
SEE SECTION A-A



Notes:

- Notes:
1. MATERIAL SPECIFICATION:
 - 1.1. HOUSING:LCP,UL94V-0,COLOR:BLACK.
 - 1.2. CONTACT:COPPER ALLOY.
 - 1.3. PEG:STEEL.
 - 1.4. GROUND BAR:STAINLESS STEEL.
 2. PLATING SPECIFICATION:
 - 2.1. CONTACT:50u" MIN.NICKEL UNDER PLATING
OVER ALL.PLATING ON SOLDER AREA:SEE TABLE
GOLD PLATING ON CONTACT AREA:SEE TABLE
 - 2.2. PEG:50u" MIN. NICKEL UNDER PLATING OVER ALL.
80u" MIN. MATTE TIN PLATING OVER ALL.
 - 2.3 GROUND BAR:50u" MIN. NICKEL UNDER PLATING OVER ALL.
50u" MIN Sn PLATING OVER ALL.
 3. HF COMPLIANT, RoHS COMPLIANT.
 4. DATE CODE:

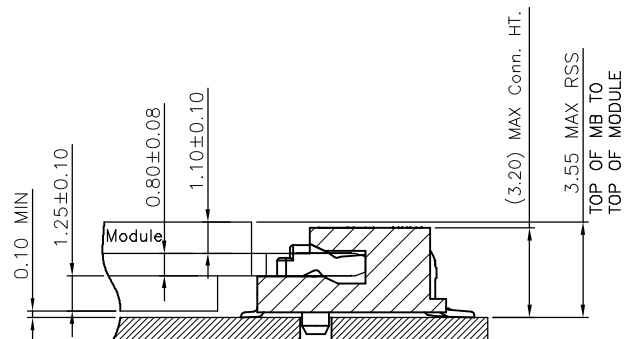
XX	XX	XX	
			DAY
			WEEK
			YEAR
 5. MECHANICAL PERFORMANCE:
 - 5.1. DURABILITY: SEE TABLE
 6. ELECTRICAL PERFORMANCE:
 - 6.1. CURRENT: 1A FOR POWER PIN. 0.5A FOR THE OTHER PIN.
REFER TO PINOUT FOR DETAILS
 - 6.2. LLCR: INITIAL 55mΩ MAX.;FINAL Δ LLCR=20mΩ MAX.
 - 6.3. OPERATING TEMPERATURE:-40°C TO 85°C .
 7. IR REFLOW:
THE TEMPERATURE SHALL BE 260±5°C MAINTAINING 10±1 SECONDS



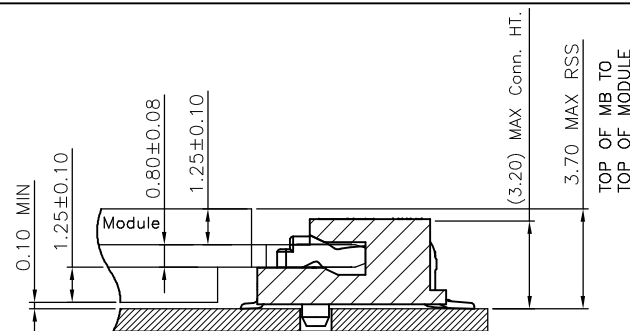
深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2' X.X* ±0.5'				NGFF M.2 M KEY 3.2H 0.5PH Gen5	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	HYC60M-05NGFF-320
		马跃	2014-02-23	MOLD NO.	
SCALE:1:1 SIZE: A4		APPROVED BY:	DATE :	DRAW NO:	HYC-2607181012
		邱敏	2014-02-23	SHEET NO.	1 OF 1

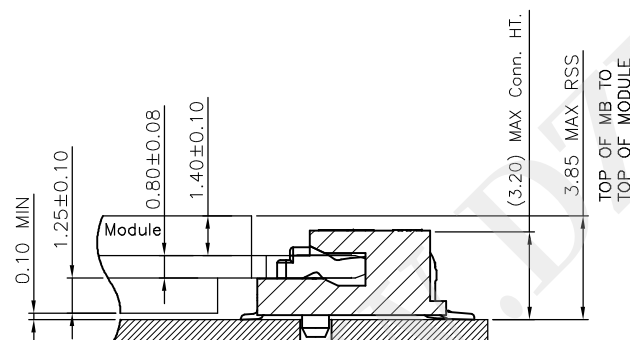
Assembly stack height schematic diagram



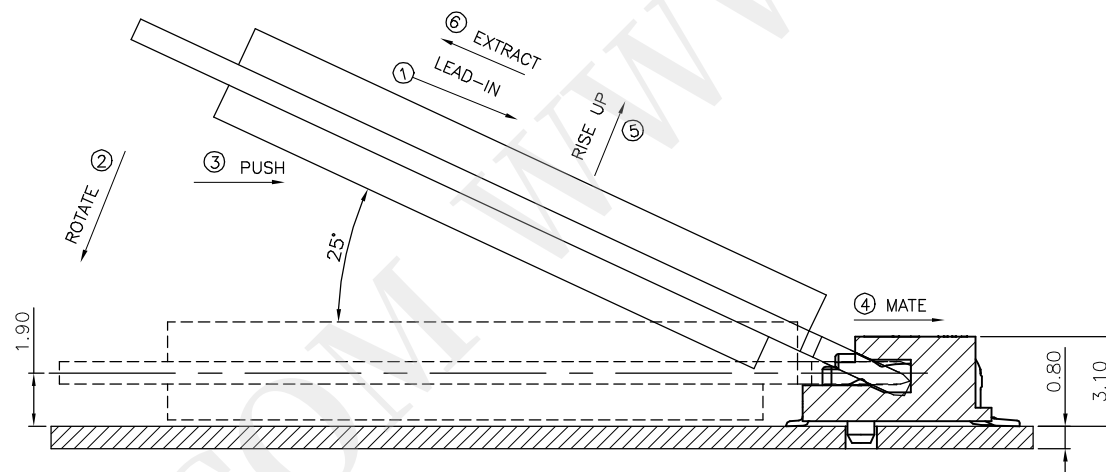
Stack-up Top Mount Double Sided Module for 1.20 max top-side component height



Stack-up Top Mount Double Sided Module for 1.35 max top-side component height



Stack-up Top Mount Double Sided Module for 1.5 max top-side component height



HOW TO MATE AND EXTRACT

MATE: ① → ④
EXTRACT: ⑤ → ⑥

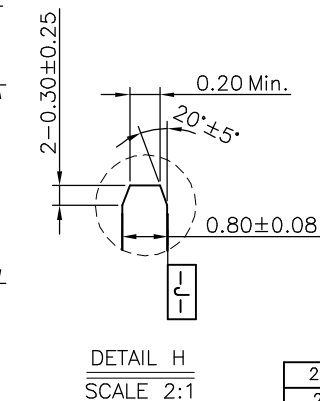
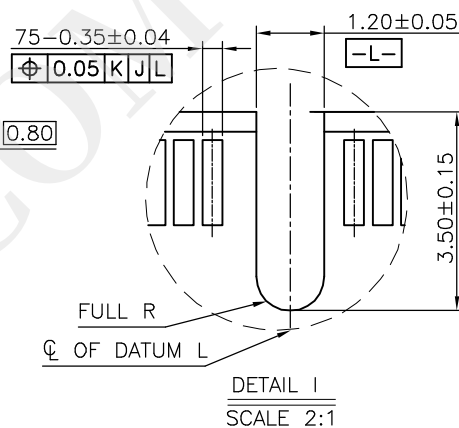
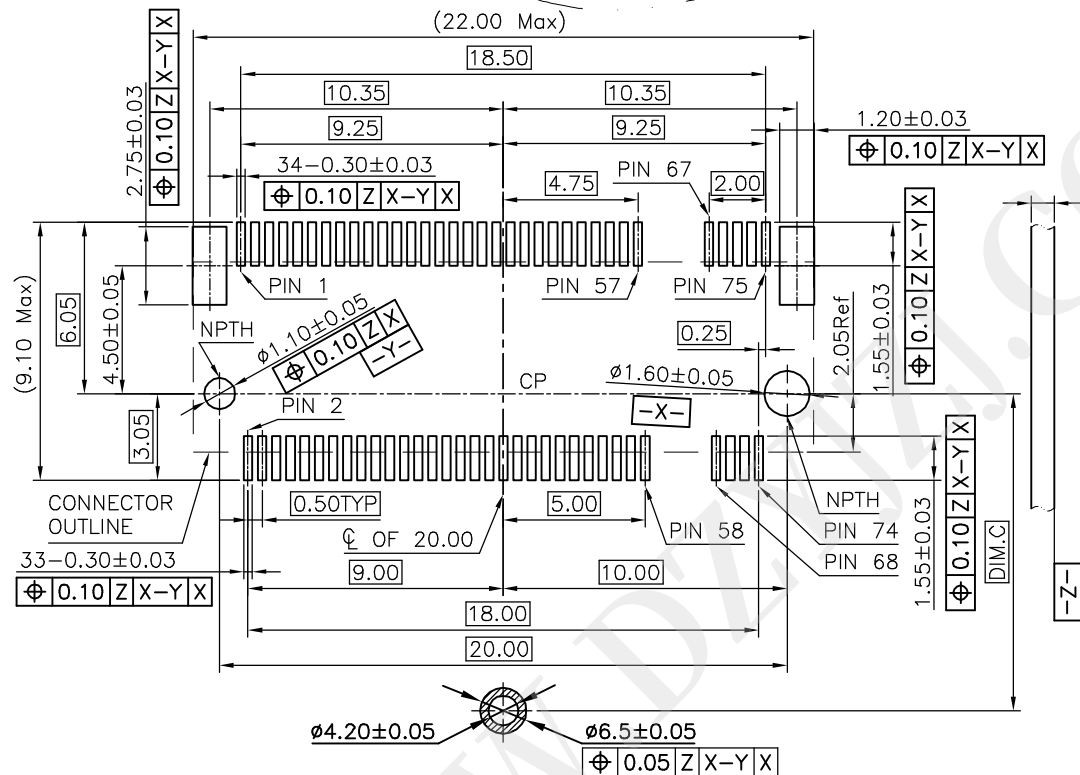
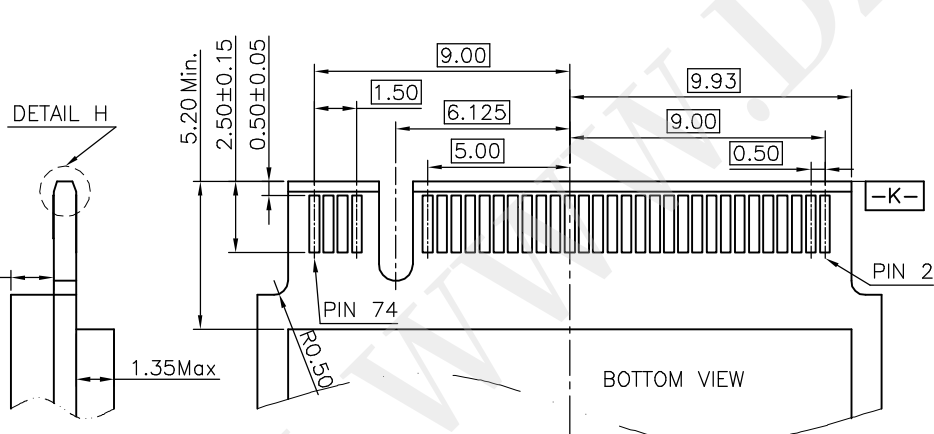
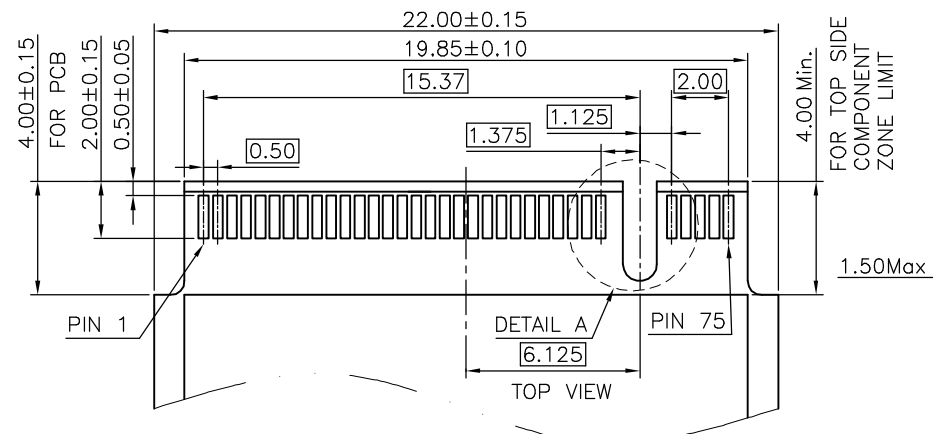
NOTE: Mating force will generate from step 3 to step 4.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NGFF M.2 M KEY 3.2H 0.5PH Gen5
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC60M-05NGFF-320
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2607181012
			SHEET NO. 1 OF 1

OPTION 1 FOR M.2 CARD



22110	108.25
2280	78.25
2260	58.25
2242	40.25
2230	28.25
3042	40.25
3030	28.25
TYPE	DIM.C

RECOMMENDED PCB LAYOUT(TOP VIEW)

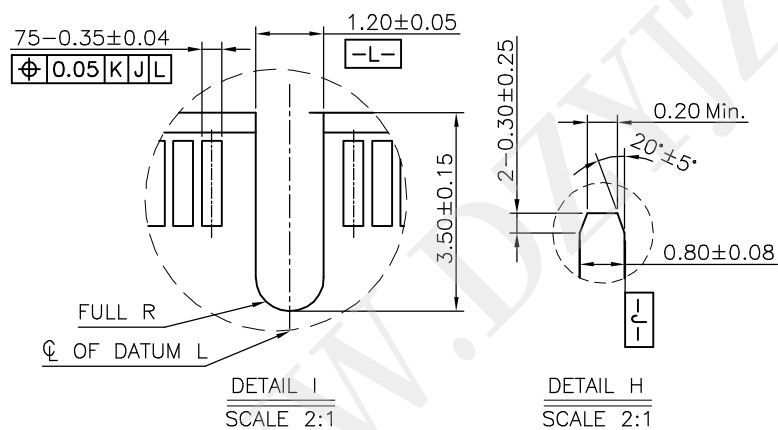
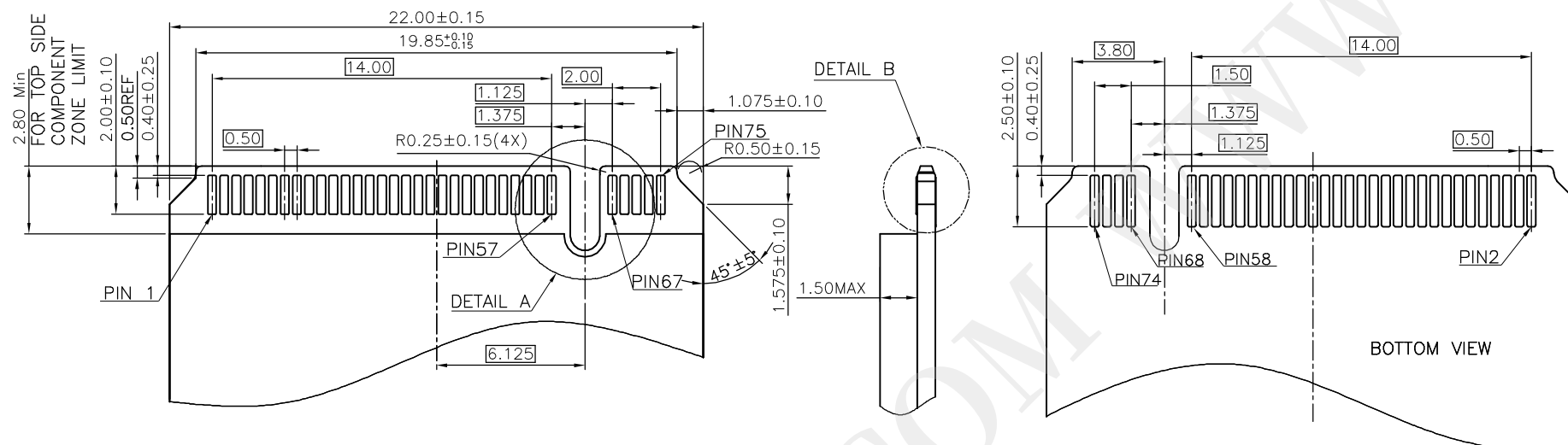
DEFAULT TOLERANCE $\pm 0.05\text{MM}$



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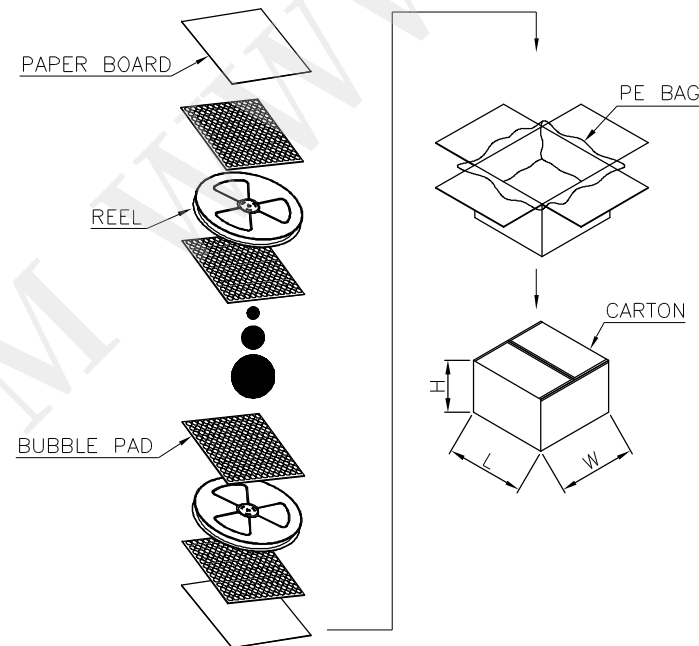
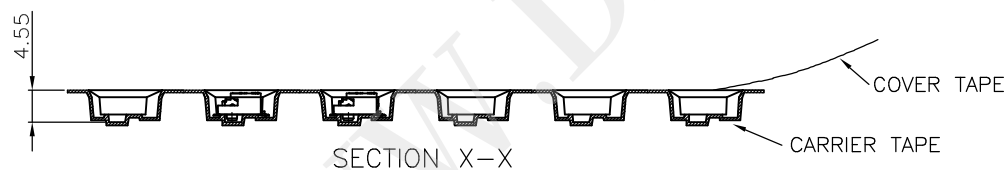
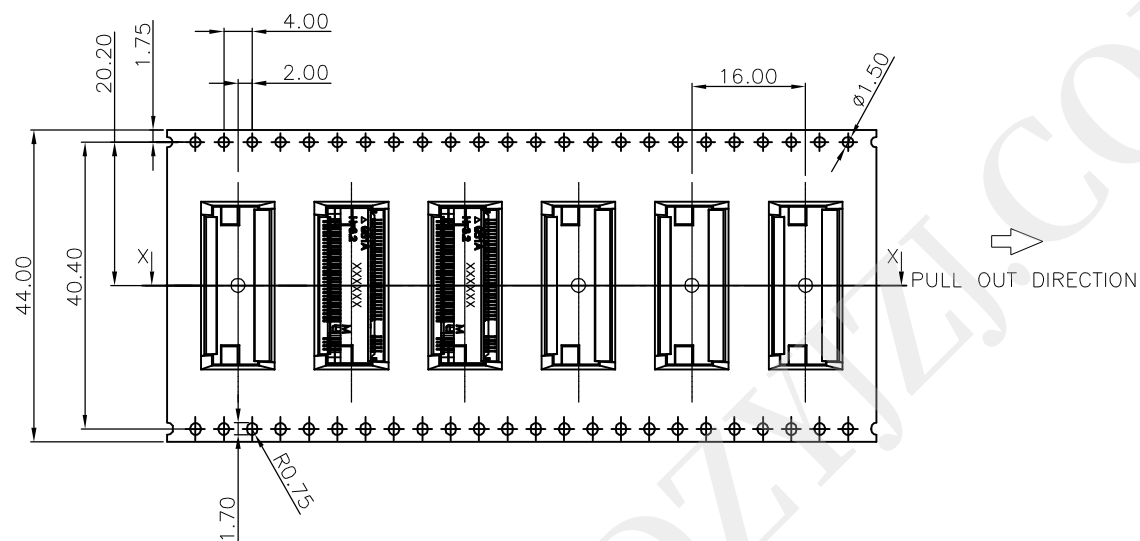
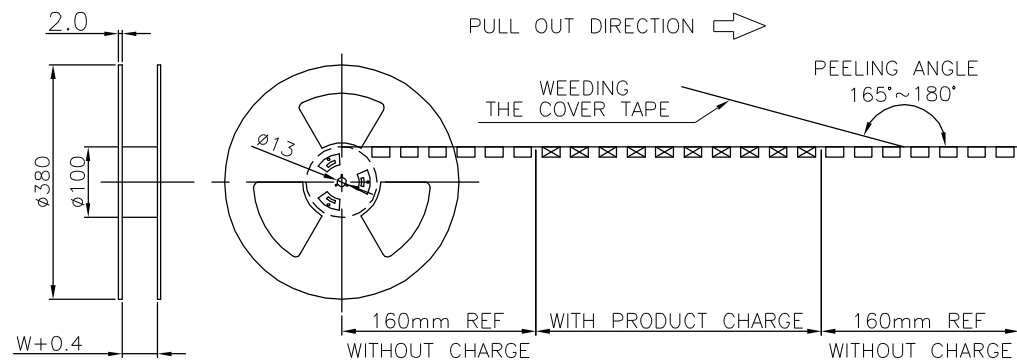
TOLERANCE:		DRAWN BY :	DATE :	PART NAME:	
X.X ±0.30		陈一鸣	2014-02-23	NGFF M.2 M KEY 3.2H 0.5PH Gen5	
X.XX ±0.25					
X.XXX ±0.15					
X.* ±2* X.X* ±0.5*		CHECKED BY:	DATE :	PART NO.	HYC60M-05NGFF-320
		马跃	2014-02-23	MOLD NO.	
UNIT: mm [inch]					
APPROVED BY:		DATE :	DRAW NO:	HYC-2607181012	
SCALE:1:1	SIZE: A4	邱敏	2014-02-23	SHEET NO.	1 OF 1

OPTION 2 FOR M.2-1A CARD



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY :	DATE :	PART NAME:	
X.X ±0.30		陈一鸣	2014-02-23	NGFF M.2 M KEY 3.2H 0.5PH Gen5	
X.XX ±0.25					
X.XXX ±0.15					
X.* ±2* X.* ±0.5*		CHECKED BY:	DATE :	PART NO.	HYC60M-05NGFF-320
		马跃	2014-02-23	MOLD NO.	
UNIT: mm [inch]				APPROVED BY:	DATE :
SCALE:1:1	SIZE: A4	邱敏	2014-02-23	SHEET NO.	1 OF 1



1200	7200
PCS/REEL	PCS/CARTON



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5' UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 包装图	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	
			SHEET NO.	1 OF 1